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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Satya et al.

Attorney Docket No.: KLA1P016F/P642

Application No.: 09/648,095

Examiner: P. Cao

Filed: August 25, 2000

Group: 2811

Title: CHEMICAL MECHANICAL POLISHING  
TEST STRUCTURES AND METHODS FOR  
INSPECTING THE SAME

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Joyce L. Ferreira

**RESPONSE TO RESTRICTION REQUIREMENT  
AND PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Restriction Requirement dated 11 December 2001, Applicants hereby elect group II, claim 7, without traverse, to prosecute in the above-identified patent application.

Additionally, Applicants also request the following amendments to the claims be entered prior to examination of such claims:

**Amendment to Claims:**

Please cancel claims 1-6 and 8-53 and add the following new claims 54-106.

54. A method of fabricating a test structure on a semiconductor die, comprising:  
forming a test structure; and  
forming a plurality of dummy fillings that are positioned and sized to minimize defects during chemical mechanical polishing, at least one of the dummy fillings being coupled to the test structure.

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